

### **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

#### **Listing of Claims:**

1. (Currently Amended) A circuit board comprising:  
an insulator plate;  
a first conductor layer ~~provided~~ bonded on one surface of the insulator plate using a bonding member;  
a second conductor layer provided in a position facing to the first conductor layer ~~on the insulator plate~~ wherein said second conductor layer is not bonded to said insulator plate by said bonding member; and  
~~a conductor electrically connected to the first~~ wherein the first conductor layer and the second conductor layer are electrically connected to one another.
2. (Original) A circuit board according to claim 1, which comprises a dielectric interposed between said first conductor layer and said second conductor layer.
3. (Original) A circuit board according to claim 1, wherein a position of an end portion of said second conductor layer is at a position of an end portion of said first conductor layer or at a position between the end portion of said first conductor layer and an end portion of said insulator plate.

4. (Original) A circuit board according to claim 1, wherein said second conductor layer comprises a layer selected from the group consisting of a metallized layer of tungsten, a metallized layer of molybdenum and manganese, a layer plated over a metallized layer of tungsten, and a layer plated over a metallized layer of molybdenum and manganese.

5. (Currently Amended) A circuit board comprising: according to claim 1,  
wherein

~~an insulator plate;~~

~~a first conductor layer provided on one surface of the insulator plate;~~

~~a second conductor layer separated from the conductor layer on the insulator plate; and~~

~~a conductor electrically connected to the first conductor layer and the second conductor layer~~ is separated from the first conductor layer.

6. (Currently Amended) A circuit board comprising:

an insulator plate;

a conductor layer ~~placed on~~ bonded to a surface of the insulator plate;

a dielectric layer provided in a gap portion between the insulator plate and the conductor layer wherein:

the following relationship exists among the dielectric constant of the dielectric layer  $\epsilon_g$ , the dielectric constant of the insulator plate  $\epsilon_b$ , the thickness of the gap portion  $L_g$ , and the thickness of the insulator plate  $L_b$ ,

$$\epsilon_g \geq \epsilon_b \times (L_g/L_b).$$